WIRE BONDING APPARATUS

ABSTRACT

Provided is a wire bonding apparatus including: a base (11); a bonding head (13) configured to move a capillary (15) in X, Y, and Z directions with respect to the base (11); and a wire-cleaning plasma unit (30). The wire-cleaning plasma unit (30) includes: hollow casings (31a), (31b) in which an inert gas is introduced so that an internal pressure is higher than an atmospheric pressure; holes (33a), (33b) respectively provided in the casings (31a), (31b) so that the wire (21) is inserted therebetween; and electrodes for plasma respectively disposed within the casings (31a), (31b) around circumferences of the holes (33a), (33b). The wire (21) is cleaned by having the wire (21) be inserted into plasma generated within the casings (31a), (31b) in a state in which air is not contained. With this, a surface of the wire used for wire bonding can be effectively cleaned.

FIGURE 1